

TITLE OF INVENTION: MANUFACTURING METHOD FOR A SUBSTRATE
WAFER

ABSTRACT

The present invention provides a substrate wafer including a central convex or a central concave warp and wherein a nanotopography in 2 mm x 2 mm in SQMM is less than 10 nm. As a result, there can be provided a substrate wafer having a warp and an excellent nanotopography.

[FIG. 1]